



INNOLAS
solutions

INNOVATION FOR THE
NEXT GENERATION



ILS-TT TURNTABLE MACHINE

POWERFUL LASER SYSTEM
FOR MICRO MATERIAL PROCESSING

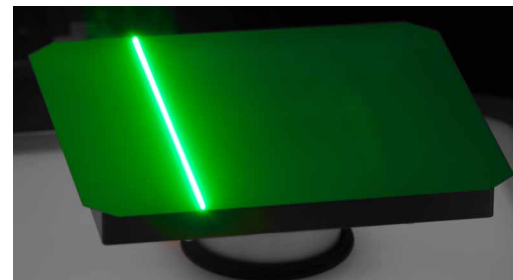
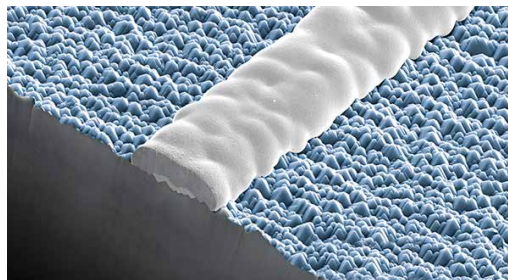
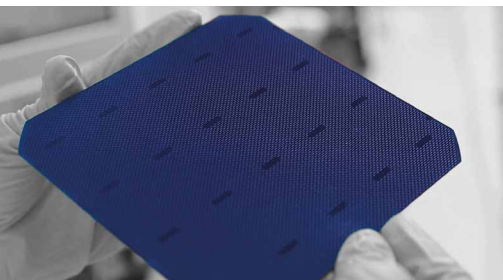


FEATURES

- ◆ Single or dual scanner setup
- ◆ Automatic camera calibration
- ◆ Automated routines for reference runs
- ◆ Automated process control
- ◆ Stand alone and production line integrated systems
- ◆ 3-, 5- or even 8-Point alignment methods available (wafer edges or fiducials)

OPTIONS

- ◆ CAD file import
- ◆ SQL data base for process and event tracking
- ◆ MES interface (SECS GEM PV2)
- ◆ Integrated process metrology
- ◆ Fully-automatic handling (production)



APPLICATIONS

Laser Contact Opening for PERC, Laser Doped Selective Emitter, Front side LCO, Laser Direct Cleaving, various applications in electronics processing

ACCURACY

< +/-35 μm (1 sigma)
 < +/-10 μm optionally
 < +/-2 μm repeatability

SUBSTRATE

Dimension up to 161 x 161 mm
 Thickness > 100 μm
 mono or poly crystalline silicon square/ pseudo square,
 ceramic, PCB

AVAILABLE LASER SOURCES

Wavelength: 1064, 1030, 532, 515, 355 nm
 Pulse: μs , ns, ps, fs

THROUGHPUT

4000 wafer per hour

